2SD0965 (2SD965)

Silicon NPN epitaxial planar type

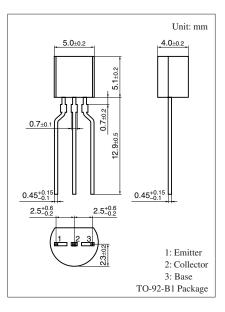
For low-frequency power amplification For stroboscope

Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Satisfactory operation performances at high efficiency with the low-voltage power supply.

Parameter	Symbol	Rating	Unit			
Collector-base voltage (Emitter open)	V _{CBO}	40	V			
Collector-emitter voltage (Base open)	V _{CEO}	20	V			
Emitter-base voltage (Collector open)	V _{EBO}	7	V			
Collector current	I _C	5	А			
Peak collector current	I _{CP}	8	А			
Collector power dissipation	P _C	750	mW			
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			





Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 1 {\rm mA}, I_{\rm B} = 0$	20			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$	7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 10 \text{ V}, I_B = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 7 V, I_C = 0$			0.1	μΑ
Forward current transfer ratio	h _{FE1} *	$V_{CE} = 2 V, I_C = 0.5 A$	230		600	
	h _{FE2}	$V_{CE} = 2 V, I_C = 1 A$	150			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 3 \text{ A}, I_{\rm B} = 0.1 \text{ A}$		0.28	1.00	V
Transition frequency	f _T	$V_{CB} = 6 V, I_E = -50 mA, f = 200 MHz$		150		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		26	50	pF
(Common base, input open circuited)						

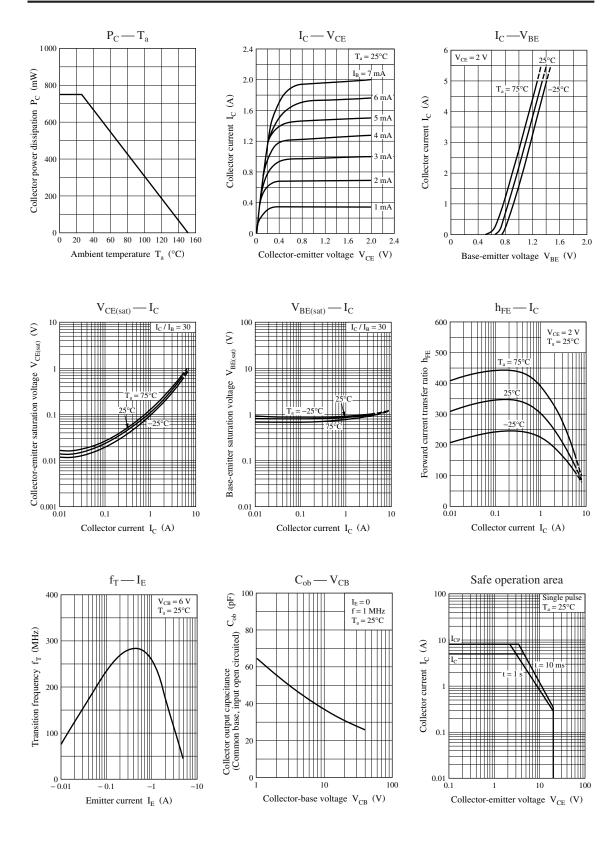
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	R
h _{FE1}	230 to 380	340 to 600

Note) The part number in the parenthesis shows conventional part number.

Panasonic



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